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Vishay Siliconix

## Automotive N-Channel 100 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY				
V <sub>DS</sub> (V)	100			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0063			
I <sub>D</sub> (A)	170			
Configuration	Single			
Package	PowerPAK SO-8L			

#### **FEATURES**

- TrenchFET® Gen IV power MOSFET
- AEC-Q101 qualified
- 100 % R<sub>q</sub> and UIS tested
- Q<sub>gd</sub>/Q<sub>gs</sub> ratio < 1 optimizes switching characteristics</li>
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912



G
N-Channel MOSFET O <sub>S</sub>

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ110EP (for detailed order number please see <a href="https://www.vishay.com/doc?79776">www.vishay.com/doc?79776</a> )

ABSOLUTE MAXIMUM RATINGS	(T <sub>C</sub> = 25 °C, unles	s otherwise noted	l)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-source voltage		V <sub>DS</sub>	100	V	
Gate-source voltage		V <sub>GS</sub>	± 20	V	
Continuous drain current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	170		
Continuous drain current	T <sub>C</sub> = 125 °C	чD	98		
Continuous source current (diode conduction)		I <sub>S</sub>	170	Α	
Pulsed drain current		I <sub>DM</sub>	224		
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	41		
Single pulse avalanche energy	L=0.11IIII	E <sub>AS</sub>	84	mJ	
Maximum power dissipation	T <sub>C</sub> = 25 °C	5 °C 500			
Maximum power dissipation	T <sub>C</sub> = 125 °C	$P_{D}$	166	VV	
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering recommendations (peak temperature) b			260		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-ambient	PCB mount a	$R_{thJA}$	42	°C/W
Junction-to-case (drain)		R <sub>thJC</sub>	0.3	G/ VV

#### Notes

- a. When mounted on 1" square PCB (FR4 material)
- b. See solder profile (<a href="www.vishay.com/doc?73257">www.vishay.com/doc?73257</a>). The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection



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PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							•
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub>	= 0, I <sub>D</sub> = 250 μA	100	-	-	V
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	= V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	2.7	3.5	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	: 0 V, V <sub>GS</sub> = ± 20 V	-	-	± 100	nA
		$V_{GS} = 0 V$	V <sub>DS</sub> = 100 V	-	-	10	μΑ
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 125 °C	-	-	50	
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 100 V, T <sub>J</sub> = 175 °C	-	-	250	
On-state drain current a	I <sub>D(on)</sub>	V <sub>GS</sub> = 10 V	$V_{DS} \ge 5 \text{ V}$	30	-	-	Α
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A	-	0.005	0.0063	
Drain-source on-state resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A, T <sub>J</sub> = 125 °C	-	-	0.0130	Ω
		V <sub>GS</sub> = 10 V	I <sub>D</sub> = 15 A, T <sub>J</sub> = 175 °C	-	-	0.0166	
Forward transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 20 A		=.	130	-	S
Dynamic <sup>b</sup>							
Input capacitance	C <sub>iss</sub>			=.	4357	6100	
Output capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	$V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$	=.	473	663	pF
Reverse transfer capacitance	C <sub>rss</sub>			-	30	42	
Total gate charge <sup>c</sup>	Qg			-	75	113	
Gate-source charge c	$Q_{gs}$	$V_{GS} = 10 \text{ V}$	$V_{DS} = 50 \text{ V}, I_{D} = 15 \text{ A}$	=.	20	-	nC
Gate-drain charge c	$Q_{gd}$			=.	15	-	
Gate resistance	Rg		f = 1 MHz	0.5	0.9	1.40	Ω
Turn-on delay time <sup>c</sup>	t <sub>d(on)</sub>			-	16	24	
Rise time <sup>c</sup>	t <sub>r</sub>	V <sub>DD</sub> =	$= 50 \text{ V}, R_L = 3.33 \Omega$	-	5	9	
Turn-off delay time <sup>c</sup>	t <sub>d(off)</sub>			54	ns		
Fall time <sup>c</sup>	t <sub>f</sub>			-	6	9	
Source-Drain Diode Ratings and Chara	acteristics <sup>b</sup>						
Pulsed current <sup>a</sup>	I <sub>SM</sub>			-	-	224	Α
Forward voltage	V <sub>SD</sub>	I <sub>F</sub> =	I <sub>F</sub> = 15 A, V <sub>GS</sub> = 0 V		-	1.1	V
Body diode reverse recovery time	t <sub>rr</sub>			=.	48	96	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	]	A di/dt = 100 A/ua	-	83	166	nC
Reverse recovery fall time	t <sub>a</sub>	] I <sub>F</sub> = 10	A, di/dt = 100 A/μs	-	33	-	
Reverse recovery rise time	t <sub>b</sub>	7		-	15	-	ns
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>			-	3.0	-	А

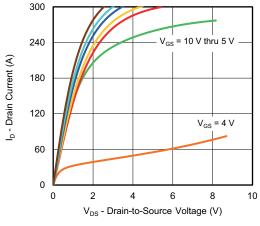
#### Notes

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

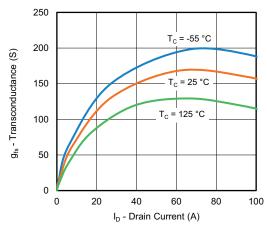
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



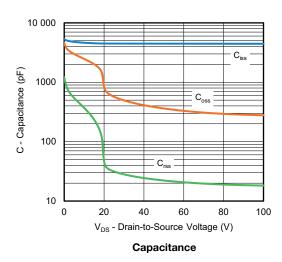
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)

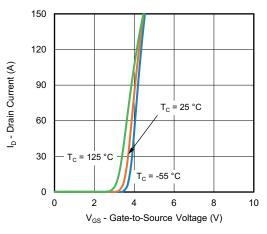


### **Output Characteristics**

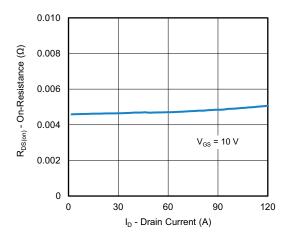


### Transconductance

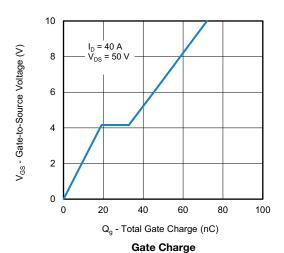




#### **Transfer Characteristics**

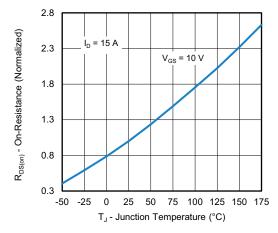


**On-Resistance vs. Drain Current** 

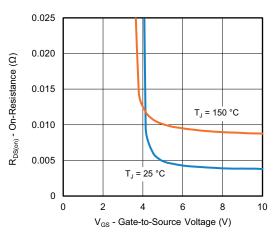




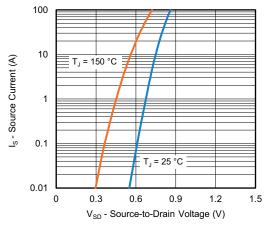
## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



On-Resistance vs. Junction Temperature

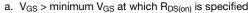


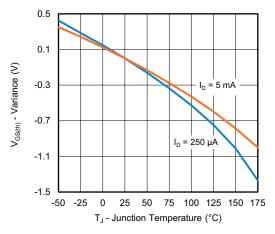
On-Resistance vs. Gate-to Source Voltage



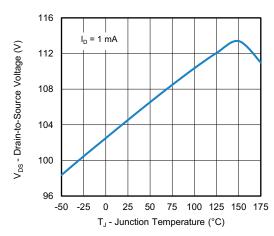
**Source Drain Diode Forward Voltage** 

Note

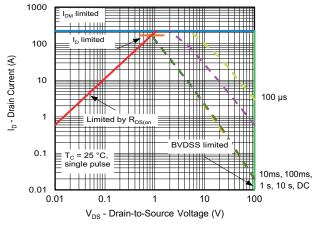




**Threshold Voltage** 



**Drain Source Breakdown vs. Junction Temperature** 

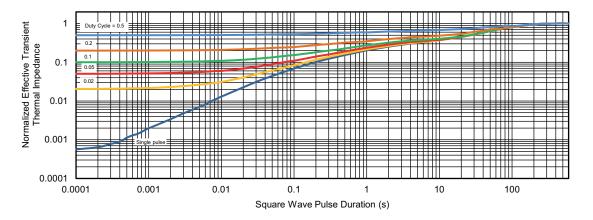


Safe Operating Area

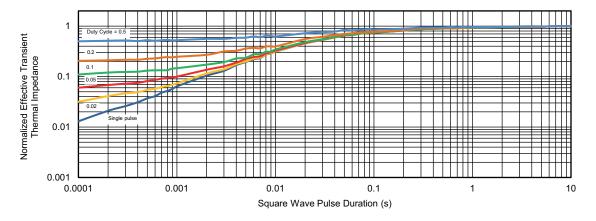
For technical questions, contact: automostechsu



## **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63151.



# PowerPAK® SO-8L (PPKSO8LWLA) Case Outline 3



DIM.		MILLIMETERS			INCHES			
DIIVI.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.		
Α	1.00	1.05	1.10	0.039	0.041	0.043		
A1	0.00		0.127	0.000		0.005		
b	0.33	0.41	0.49	0.013	0.016	0.019		
b1	0.43	0.51	0.59	0.017	0.020	0.023		
b2	4.00	4.10	4.20	0.157	0.161	0.165		
С	0.15	0.20	0.25	0.006	0.008	0.010		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D5	0.51	0.61	0.71	0.020	0.024	0.028		
D6	2.64	2.74	2.84	0.104	0.108	0.112		
е		1.27 BSC		0.050 BSC				
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	3.18	3.28	3.38	0.125	0.129	0.133		
E3	3.48	3.58	3.68	0.137	0.141	0.145		
E4	2.72	2.82	2.92	0.107	0.111	0.115		
E5	0.71	0.81	0.91	0.028	0.032	0.036		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
W1	0.31	0.41	0.51	0.012	0.016	0.020		
W4	0.31	0.36	0.41	0.012	0.014	0.016		
z1	0.37	0.47	0.57	0.015	0.019	0.022		
z2	0.99	1.09	1.19	0.039	0.043	0.047		
θ	0°		5°	0°		5°		

#### Note

• Millimeter will govern

Revison: 18-Sep-2023 1 Document Number: 76666



# Recommended Land Pattern PowerPAK® SO-8L Single Short Ear



Dimensions in Millimeters (Inches)

Revision: 24-Aug-2021 1 Document Number: 78020



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